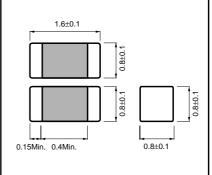
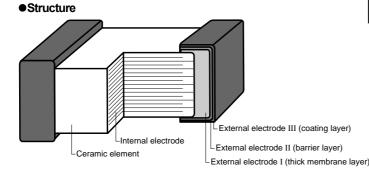
Multi-layer ceramic chip capacitors MCH18 (1608 (0603) size, chip capacitor)

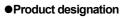
Features

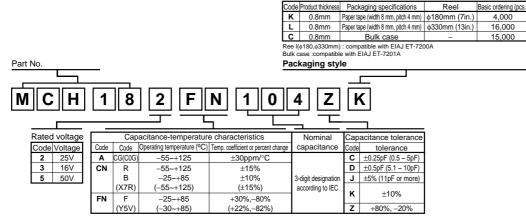
- 1) Small size (1.6 x 0.8 x 0.8 mm) makes it perfect for lightweight portable devices.
- Comes packed either in tape to enable automatic mounting or in bulk cases.
- Precise uniformity of shape and dimentions highly efficient automatic mounting.
- Barrier layer and end terminations to improve solderability.









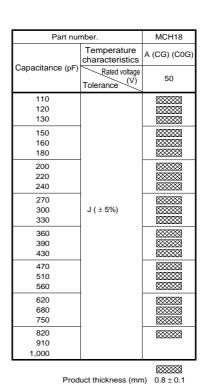




Capacitance range

For thermal compensation

Part nur	MCH18		
, arthu			
0	Temperature characteristics	A (CG) (C0G)	
Capacitance(pF)	Rated voltage	50	
	Tolerance (V)		
0.5			
0.75 1			
1.1			
1.2			
1.3			
1.5			
1.6 1.8			
2			
2.2	C (±0.25pF)		
2.4			
2.7 3			
3.3			
3.6	1		
3.9 4 4.3 4.7			
5			
5.1			
5.6 6			
6.2			
6.8			
7	D (± 0.5pF)		
7.5 8			
8.2			
9			
9.1 10			
10			
12			
13			
15 16			
16 18			
20			
22			
24			
27 30	J (±5%)		
33			
36			
39 43			
43			
47 51			
56			
62			
68 75			
82	1		
91			
100			





High dielectric constant

Part number		MCH18				
Capacitance(pF)	Temperature characteristics	CN (R) (B) (X7R)		FN (F) (Y5V)		
	Rated voltage (V)	50	25	50	25	16
	Tolerance	K (±	10%)	Z	Z (+80%, -20%)	
220						
270 330						
330		<u> xxxxxxx</u>				
390 470						
560						
680						
820		XXXXXX		NXXXXX		
1,000						
1,200 1,500						
1,800						
2,200						
2,700		8888888				
3,300						
3,900 4,700						
5,600						
6,800						
8,200						
10,000 (0.01µF)						
12,000 15,000						
18,000						
22,000						
27,000			~~~~~			
33,000						
39,000 47,000						
56,000						
68,000						
82,000			N		N	
100,000 (0.1µF)						
120,000 150,000						
180,000						
220,000						
270,000						
330,000						
390,000 470,000						
560,000						
680,000						
1,000,000 (1µF) 1,200,000						
1,500,000						
1,800,000						
2,200,000						

Product thickness (mm) 0.8 ± 0.1



Characteristics

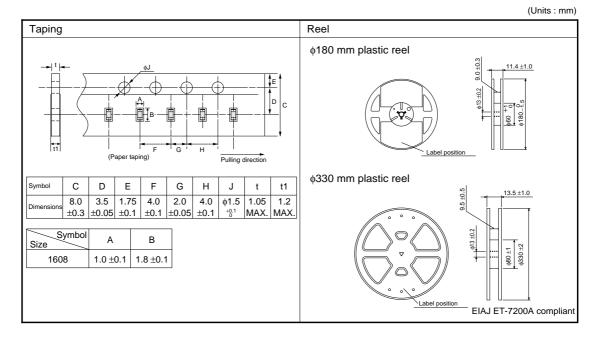
Class 1 (For thermal compensation)

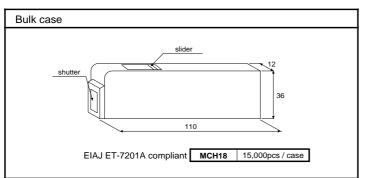
Temperature characteristics		A (CG) (C0G)	Test methods / conditions (based on JIS C 5102)	
Operating temperature		-55°C ~ +125°C		
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 and paragraph 9 Measured at room temperature and standard humidity 1000pF or less Measurement frequency : 1± 0.1MHz	
Dissipation factor $(\tan \delta)$		100 / (400 + 20C)% or less (Less than 30 pF) 0.1% or less (30 pF or larger)	Measurement voltage : 1± 0.1Vrm Over 1000pF Measurement frequency : 1± 0.1kHz Measurement voltage : 1± 0.1Vrm	
Insulation resistance (IR)		$10{,}000M\Omega$ or $500M\Omega{\cdot}\mu F$, whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60 \pm 5s$.	
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 300% of the rated voltage for 1 to 5s then measure.	
Temperature characteristics		Within 0 \pm 30ppm / $^{\circ}\text{C}$	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11.2 Apply SN for 10 ± 1s in the direction indicated by the arrow. Pressure (5N) Capacitor	
Resistance to vibration	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
	Rate of capacitance change	Must be within initial tolerance.		
	Dissipation factor (tanδ)	Must satisfy initial specified value.	and measured 24 \pm 2 hrs. later. Board	
Solderability		At least 3 / 4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature : 235 ± 5°C Soldering time : 2 ± 0.5s	
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	\pm 2.5% or \pm 0.25 pF , whichever is larger.	Based on paragraph 8.14	
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.	Soldering temperature : $260 \pm 5^{\circ}$ C Soldering time : 5 ± 0.5 s	
heat	Insulation resistance	10,000 M\Omega or 500 M\Omega μF , whichever is smaller	Preheating : 150 ± 10°C for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.	1.0211111.	
	Appearance	There must be no mechanical damage.		
Temperature	Rate of capacitance change	\pm 2.5% \pm 0.25 pF , whichever is larger.	Based on paragraph 9.3	
cycling	Dissipation factor (tan)	Must satisfy initial specified value.	Number of cycles : 5 Capacitance measured after 24 ± 2 hrs.	
	Insulation resistance	10,000 M\Omega or 500 M\Omega μF , whichever is smaller		
Humidity load - test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9 Test temperature : 40 ± 2°C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs.	
	Rate of capacitance change	\pm 7.5% or \pm 0.75 pF , whichever is larger.		
	Dissipation factor (tanδ)	0.5% or less		
	Insulation resistance	$500 M\Omega$ or $25 M\Omega \cdot \mu F$, whichever is smaller	Capacitance measured after 24 ± 2 hrs.	
High- temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10	
	Rate of capacitance change	\pm 3.0% or \pm 0.3 pF , whichever is larger.	Test temperature : Max. operating temp.	
	Dissipation factor (tanδ)	0.3% or less	Applied voltage : rated voltage × 2 Test time : 1,000 to 1,048 hr	
	Insulation resistance	1,000M\Omega or $50 M\Omega {\cdot} \mu F$, whichever is smaller	Capacitance measured after 24 ± 2 hrs.	



	Temperature characteristics	CN (R) (B) (X7R)	FN (F) (Y5V)	Test methods/conditions (based on JIS C 5102)	
Item					
Operating temperature		−55°C ~ +125°C	−30°C ~ +85°C		
Nominal capacitance (C)		Must be within the specified tolerance range.		Based on paragraph 7.8 Measured at room temperature and standard humidi	
Dissipation factor (tanδ)		2.5% or less (when rated voltage is 16V: 3.5% or less) (when rated voltage is 16V: 7.5% or less)		Measurement frequency: 1 ± 0.1 kHz	
Insulation resistance (IR)		10,000 M\Omega or 500 M\Omega $\cdot\mu\text{F},$ whichever is smaller		Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60 \pm 5s$.	
Withstanding voltage		The insulation must not be damaged.		Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measu	
Temperature c	haracteristics	Within \pm 15%	+ 22, + 82%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20° C, with no voltage applied.	
Terminal adherence		No detachment or signs of detachment		Based on paragraph 8. 11. 2. Apply 5N for 10 ± 1s in the direction indicated by the arrow.	
	Appearance	There must be no mechanical damage.		Chip is mounted to a board in the	
Resistance to vibration	Rate of capacitance change	e Must be within initial tolerance.		manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
	Dissipation factor (tan δ)	Must satisfy initial specified value.		and measured 48 \pm 4 hrs. later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.		$\begin{array}{llllllllllllllllllllllllllllllllllll$	
	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 5.0%	Within ± 20.0%	Based on paragraph 8. 14.	
Resistance to soldering	Dissipation factor (tan δ)	Must satisfy initia	al specified value.	Soldering temperature: 260 ± 5°C	
heat	Insulation resistance	10,000M\Omega or 500M\Omega $\cdot\mu\text{F},$ whichever is smaller		Soldering time: $5 \pm 0.5s$ Preheating: $150 \pm 10^{\circ}C$ for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.			
	Appearance	There must be no n	nechanical damage.		
Temperature	Rate of capacitance change	Within \pm 7.5%	Within $\pm 20.0\%$	Based on paragraph 9.3 Number of cycles : 5	
cycling	Dissipation factor (tan δ)	Must satisfy initial specified value.		Capacitance measured after 48 \pm 4	
	Insulation resistance	10,000M\Omega or 500M\Omega $\cdot\mu\text{F},$ whichever is smaller			
Humidity load test	Appearance	There must be no mechanical damage.		Based on paragraph 9.9	
	Rate of capacitance change	± 12.5% or less	Within ± 30.0%	Test temperature: 40 ± 2°C	
	Dissipation factor (tan δ)	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Relative humidity: 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs.	
	Insulation resistance	500M\Omega or 25M $\Omega \cdot \mu F$, whichever is smaller		Capacitance measured after 48 ± 4 hr	
High- temperature load test	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 10.0%	Within ± 30.0%	Based on paragraph 9.10	
	Dissipation factor $(tan \delta)$	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Test temperature: Max. operating tem Applied voltage : rated voltage × 200 Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000M Ω or 50M $\Omega \cdot \mu F$, whichever is smaller		Capacitance measured after 48 ± -	





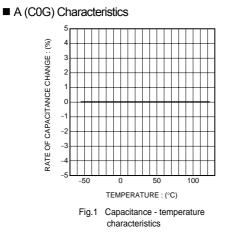




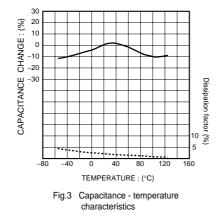
MCH18

Ceramic capacitors

•Electrical characteristics



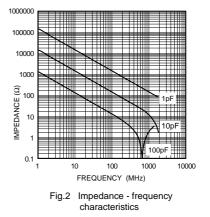
■CN (X7R) Characteristics

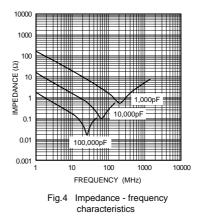


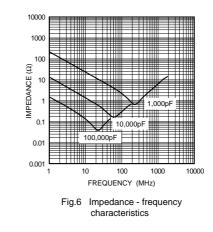
TEMPERATURE : (°C)

Fig.5 Capacitance - temperature

characteristics







■FN (Y5V) Characteristics 20

10 0 (%)

-10

-80

-80 -40 0 40 80 120 160

CAPACITANCE CHANGE : -20 -30 -40 -50 -60 -70

*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

Dissipation factor (%)

50 40

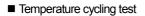
30 20

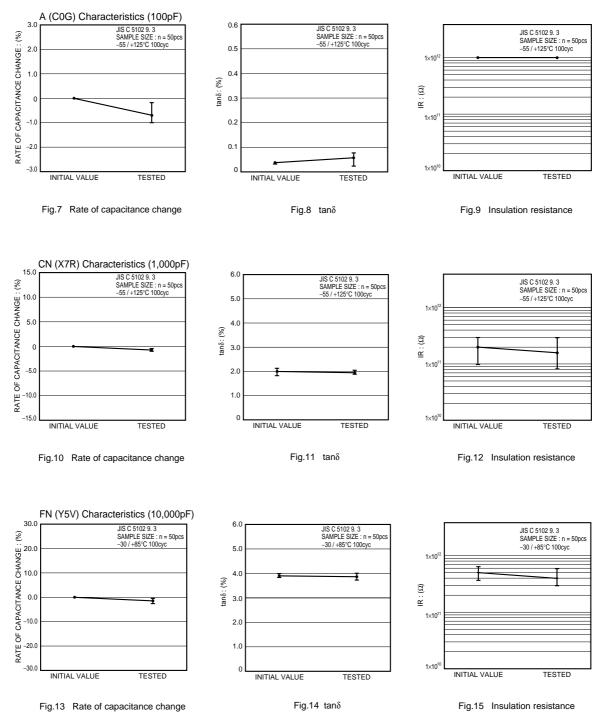
10



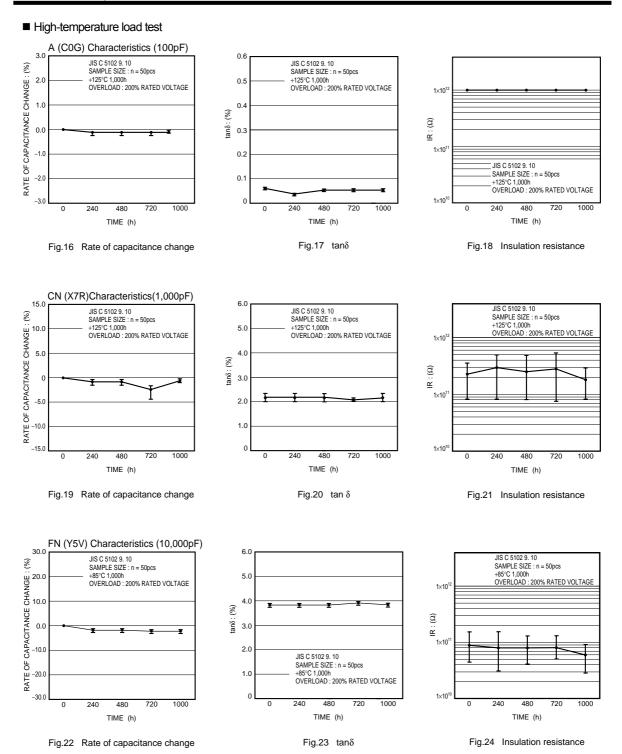
MCH18

Ceramic capacitors











Humidity load test

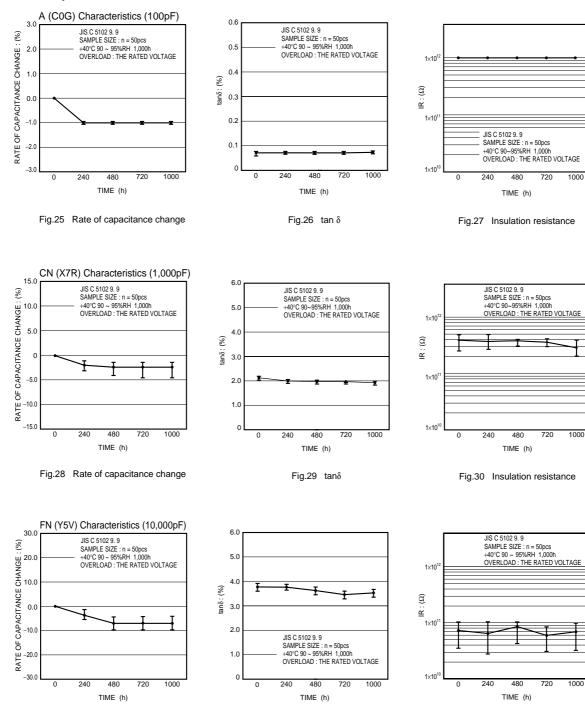


Fig.31 Rate of capacitance change

Fig.33 Insulation resistance

*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.



Fig.32 tano